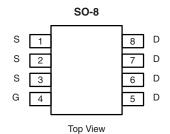


N-Channel 80 V (D-S) Super Trench Power MOSFET

| PRODUCT SUMMARY | | | | | |
|---|--------|--|--|--|--|
| V _{DS} (V) | 80 | | | | |
| $R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$ | 0.010 | | | | |
| $R_{DS(on)}(\Omega)$ at $V_{GS} = 6 \text{ V}$ | 0.012 | | | | |
| I _D (A) | 12 | | | | |
| Configuration | Single | | | | |



FEATURES

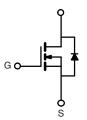
- Super Trench technology Power MOSFET
- Excellent gate charge x Rds (on) product(FOM)
- Very low on-resfistance Rds (on)
- \bullet 100 % R_g and UIS Tested

Pb-free

ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- DC/DC Converter
- Ideal for hfigh-frequency swfitchfing and synchronous



N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted) | | | | | |
|--|-------------------------|-----------------------------------|---------------|------|--|
| PARAMETER | | SYMBOL | LIMIT | UNIT | |
| Drain-Source Voltage | | V_{DS} | 80 | V | |
| Gate-Source Voltage | | V_{GS} | ± 20 | V | |
| Continuous Drain Current | T _C = 25 °C | 1 | 12 | | |
| Continuous Drain Current | T _C = 125 °C | - I _D | 7 | | |
| Continuous Source Current (Diode Conduction) | I _S | 6 | Α | | |
| Pulsed Drain Current ^a | | I _{DM} | 67 | | |
| Single Pulse Avalanche Current | L = 0.1 mH | I _{AS} | 50 | | |
| Single Pulse Avalanche Energy | L = 0.1 IIIA | E _{AS} | 125 | mJ | |
| Maximum Power Dissipation ^a | T _C = 25 °C | P _D | 7.1 | W | |
| Maximum Tower Dissipation- | T _C = 125 °C | r _D | 2.3 | VV | |
| Operating Junction and Storage Temperature Range |) | T _J , T _{stg} | - 55 to + 175 | °C | |

| THERMAL RESISTANCE RATINGS | | | | | | |
|----------------------------|------------------------|------------|-------|------|--|--|
| PARAMETER | | SYMBOL | LIMIT | UNIT | | |
| Junction-to-Ambient | PCB Mount ^b | R_{thJA} | 80 | °C/W | | |
| Junction-to-Foot (Drain) | | R_{thJF} | 21 | C/VV | | |

Notes

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. When mounted on 1" square PCB (FR-4 material).
- c. Parametric verification ongoing.

IRF7854TRPBF



| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|---|--------------------------|--|---|------|-------|-------|------|
| Static | | | | | ' | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0$, $I_D = 250 \mu A$ | | 80 | - | - | V |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 \mu A$ | | 2.5 | 3.0 | 3.5 |) v |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | - | - | ± 100 | nA |
| | | $V_{GS} = 0 V$ | V _{DS} = 60 V | - | - | 1.0 | μА |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{GS} = 0 V$ | V _{DS} = 80 V, T _J = 125 °C | 1 | - | 50 | |
| | | V _{GS} = 0 V | V _{DS} = 80 V, T _J = 175 °C | - | - | 250 | |
| On-State Drain Current ^a | I _{D(on)} | V _{GS} = 10 V | $V_{DS} \ge 5 V$ | 30 | - | - | Α |
| | | V _{GS} = 10 V | I _D = 6 A | - | 0.010 | - | Ω |
| Drain Course On State Resistance | | V _{GS} = 10 V | I _D = 6 A, T _J = 125 °C | | 0.015 | - | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = 10 V | I _D = 6 A, T _J = 175 °C | | 0.020 | - | |
| | | V _{GS} = 6 V | I _D = 5 A | - | 0.012 | - | |
| Forward Transconductance ^b | 9 _{fs} | V _{DS} = 15 V, I _D = 6 A | | - | 25 | - | S |
| Dynamic ^b | | | | | | | |
| Input Capacitance | C _{iss} | | | - | 2531 | 3165 | |
| Output Capacitance | C _{oss} | $V_{GS} = 0 \text{ V}$ $V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$ | - | 382 | 480 | pF | |
| Reverse Transfer Capacitance | C _{rss} | | | - | 153 | 195 | 1 |
| Total Gate Charge ^c | Qg | | | - | 45 | 68 | |
| Gate-Source Charge ^c | Q _{gs} | V _{GS} = 10 V | $V_{DS} = 30 \text{ V}, I_{D} = 12 \text{ A}$ | - | 9.9 | - | nC |
| Gate-Drain Charge ^c | Q _{gd} | | | - | 11.2 | - |] |
| Gate Resistance | R _g | f = 1 MHz | | 0.40 | 0.87 | 1.30 | Ω |
| Turn-On Delay Time ^c | t _{d(on)} | | | | 13 | 20 | |
| Rise Time ^c | t _r | $V_{DD} = 30 \text{ V}, \text{ R}_L = 2.5 \Omega$ $I_D \cong 12 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$ | | - | 12 | 18 | ns |
| Turn-Off Delay Time ^c | t _{d(off)} | | | - | 25 | 38 | |
| Fall Time ^c | t _f | | | - | 9 | 14 | |
| Source-Drain Diode Ratings and Char | acteristics ^b | | | | | | |
| Pulsed Current ^a | I _{SM} | | | - | - | 67 | Α |
| Forward Voltage | V_{SD} | $I_F = 1.7 \text{ A}, V_{GS} = 0$ | | - | 0.72 | 1.2 | V |

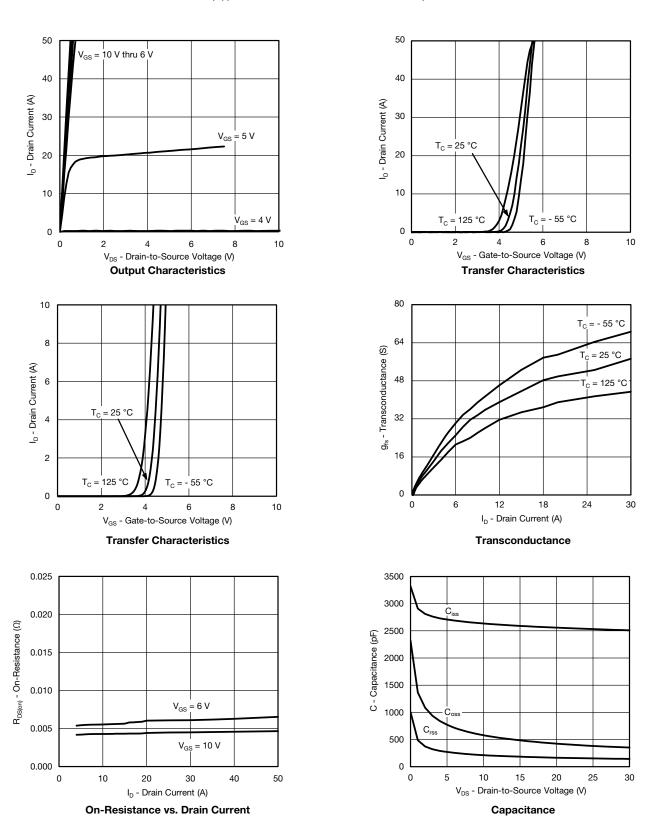
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

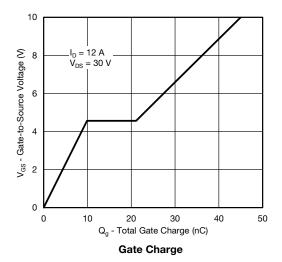


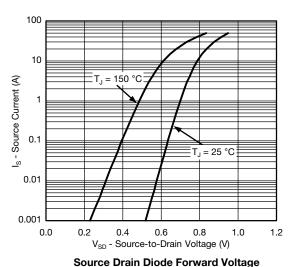
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

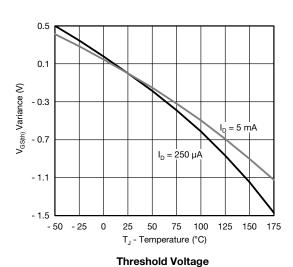


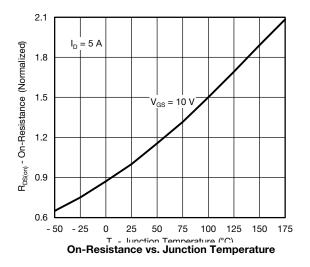


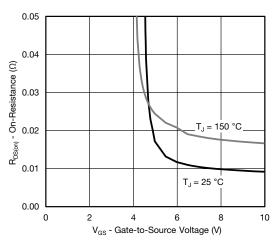
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



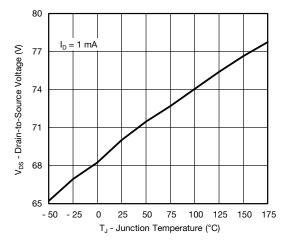








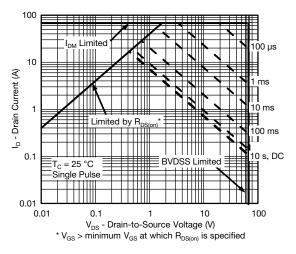
On-Resistance vs. Gate-to-Source Voltage



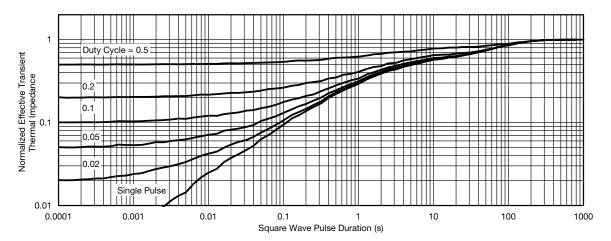
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



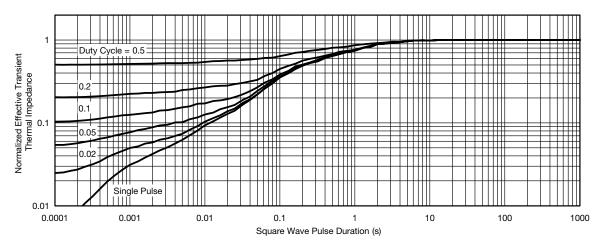
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot

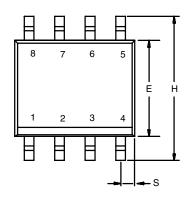
Note

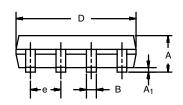
- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C)

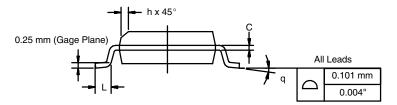
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







| | MILLIM | IETERS | INCHES | | |
|------------------------------|--------|--------|-----------|-------|--|
| DIM | Min | Max | Min | Max | |
| Α | 1.35 | 1.75 | 0.053 | 0.069 | |
| A ₁ | 0.10 | 0.20 | 0.004 | 0.008 | |
| В | 0.35 | 0.51 | 0.014 | 0.020 | |
| С | 0.19 | 0.25 | 0.0075 | 0.010 | |
| D | 4.80 | 5.00 | 0.189 | 0.196 | |
| Е | 3.80 | 4.00 | 0.150 | 0.157 | |
| е | 1.27 | BSC | 0.050 BSC | | |
| Н | 5.80 | 6.20 | 0.228 | 0.244 | |
| h | 0.25 | 0.50 | 0.010 | 0.020 | |
| L | 0.50 | 0.93 | 0.020 | 0.037 | |
| q | 0° | 8° | 0° | 8° | |
| S | 0.44 | 0.64 | 0.018 | 0.026 | |
| ECN: C 06527 Pay 1 11 Cap 06 | | | | | |

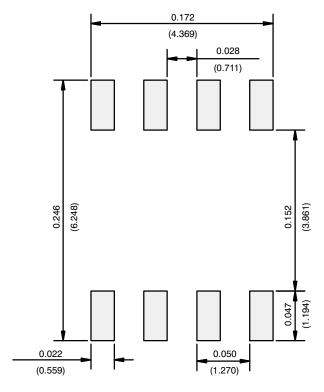
ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498

8



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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